Product Change Notification - LIAL-31KHQG947

Date:

02 Apr 2020

Product Category:

Automotive LED Drivers; EL Backlight Driver ICs; General Purpose LED Drivers

Affected CPNs:



Notification subject:

CCB 4178 Initial Notice: Qualification of NSEB as new assembly site for selected AT991xx, HV85xx and HV99xx device families available in 8L WDFN (3x3x0.8mm) package.

Notification text:

PCN Status:

Initial notification.

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of NSEB as new assembly site for selected AT991xx, HV85xx and HV99xx device families available in 8L WDFN (3x3x0.8mm) package.

Pre Change:

Assembled at CARC using QMI519 die attach and EME-G770HCD molding compound material

Post Change:

Assembled at NSEB using 8600 die attach and G700LTD molding compound material

Pre and Post Change Summary:

	Pre Change	Post Change				
Assembly Site	Caraam (Suzhau)	UTAC Thai Limited (UTL-				
	Carsem (Suzhou) (CARC)	1) LTD.				
	(CANO)	(NSEB)				
Wire material	Au	Au				
Die attach material	QMI519	8600				
Molding compound	EME-G770HCD	G700LTD				
material	LIVIL-G170110D	GIOOLID				
Lead frame material	A194	A194				

Impacts to Data Sheet:

None

Change Impact:



None

Reason for Change:

To improve manufacturability by qualifying NSEB as a new assembly site.

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

July 2020

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

		April 2020					July 2020				
	14	15	16	17	18	>	27	28	20	30	31
Initial PCN Issue Date	X										
Qual Report Availability											X
Final PCN Issue Date											X

Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN # Qual Plan.

Revision History:

April 2, 2020: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products

Attachment(s):

PCN LIAL-31KHQG947 QUAL PLAN.pdf

Please contact your local <u>Microchip sales office</u> with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our <u>PCN home page</u> select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the <u>PCN FAQ</u> section.

If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and



make the applicable selections.

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Affected Catalog Part Numbers (CPN)

HV857LK7-G

HV857K7-G

HV859K7-G

HV9918K7-G

AT9919K7-G

AT9919K7-GVAO

HV9919BK7-G

HV9967BK7-G

Date: Wednesday, April 01, 2020